

HPW

PATENT

Docket No.: 4425-336

JAN 05 2005



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hsin-Chang WU : Confirmation No. 7178

U.S. Patent Application No. 10/722,394 : Group Art Unit: 2823

Filed: November 28, 2003 : Examiner: TRUNG Q. DANG

For: METHOD AND STRUCTURE FOR THE ADHESION BETWEEN DIELECTRIC LAYERS

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

No additional fee is required.  
 Small entity status of this application has been established.  
 Also attached:

The fee has been calculated as shown below:

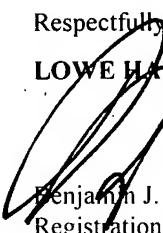
	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	18	20	0	x \$ 18 =	\$ 0.00
Independent Claims	3	3	0	x \$ 88 =	\$ 0.00
If multiple claims newly presented, add \$290.00					
Fee for extension of time					
<b>TOTAL FEE DUE</b>					<b>\$ 0.00</b>

A credit card authorization form in the amount of \_\_\_\_\_ is attached

The Commissioner is hereby authorized to charge payment of any *deficiency* in fees associated with this communication or credit any overpayment, to Deposit Account No. 07-1337, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

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Date: January 5, 2005

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/722,394 Confirmation No. 7178  
Applicant : Wu, Hsin-Chang  
Filed : November 28, 2003  
TC/A.U. : 2823  
Examiner : Dang, Trung Q  
Docket No. : 4425-336  
Title : METHOD AND STRUCTURE FOR THE ADHESION  
BETWEEN DIELECTRIC LAYERS

**AMENDMENT**

Honorable Commissioner for Patent  
P. O. Box 1450  
Alexandria VA 22313-1450

Sir:

In response to the Office Action of October 05, 2004, in connection with the above-identified application, please amend the above-identified application as follows:

**Amendments to the Claims:** are reflected in the listing of claims, which begins on page 2 of this paper.

**REMARKS/ARGUMENTS** begin on page 6 of this paper.